

ABSTRACT

An optoelectronic semiconductor package device includes a semiconductor chip, an insulative housing and a conductive trace, wherein the chip includes an upper surface and a lower surface, the upper surface includes a light sensitive cell and a conductive pad, the insulative housing includes a first single-piece non-transparent insulative housing portion that contacts the lower surface and is spaced from the light sensitive cell and a second transparent insulative housing portion that contacts the first housing portion and the light sensitive cell, and the conductive trace extends outside the insulative housing and is electrically connected to the pad inside the insulative housing.